KBJ6005 THRU KBJ610

GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER



REVERSE VOLTAGE: 50 to 1000 VOLTS FORWARD CURRENT: 6.0 AMPERE

FEATURES

· Glass passivated chip junction

· Reliable low cost construction utilizing molded plastic technique

· Ideal for printed circuit board

· Low forward voltage drop

· Low reverse leakage current

· High surge current capability

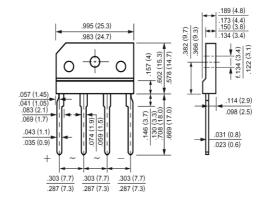
MECHANICAL DATA

Case: Molded plastic, KBJ

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202,

method 208 guaranteed Mounting position: Any Weight: 0.16ounce, 4.6gram KBJ



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

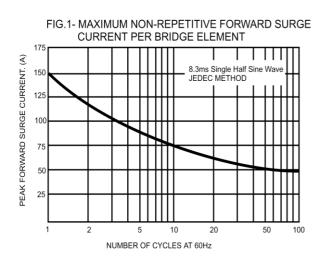
	Symbols	KBJ6005	KBJ601	KBJ602	KBJ604	KBJ606	KBJ608	KBJ610	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current at T_C =110	I _(AV)	6.0							Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I _{FSM}	150							Amp
Maximum Forward Voltage at 3.0A DC and 25	V_{F}	1.0							Volts
	I_R	5.0 500							uAmp
Typical Junction Capacitance (Note 1)	C_{J}	80							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JC}$	1.5							/W
Operating and Storage Temperature Range	T _J , Tstg	-55 to +150							

NOTES:

- 1- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.
- 2- Thermal Resistance from Junction to Case with Device Mounted on 75mm x 75mm x 1.6mmCu Plate Heatsink.



RATINGS AND CHARACTERISTIC CURVES



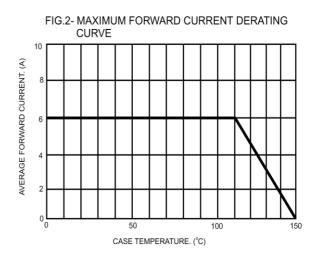


FIG.3- TYPICAL INSTANTANEOUS FORWARD
CHARACTERISTICS PER BRIDGE ELEMENT

